

A B S T R A C T

EPOXY RESIN COMPOSITION FOR SEMICONDUCTOR ENCAPSULATION

An epoxy resin composition for semiconductor encapsulation containing at least an epoxy resin, hardener, inorganic filler, and accelerator, wherein said epoxy resin is one which is composed of 20-90 parts by weight of 4,4'-bisphenol F type epoxy resin and 10-80 parts by weight of either a polyhydric phenolic type epoxy resin which has slightly polar hydrocarbon groups (Z) lying between the phenyl nuclei, or a biphenol type epoxy resin.

The composition is superior in fluidity and gives a cured product having low moisture absorption and good solder crack resistance and heat resistance. It is suitable for encapsulation of semiconductors.